

FEATURES

Surface Mounting Design 8.3*8.3*6.0mm

High Current Handling Capability 20000A @ 8/20 μs

Low Capacitance and Insertion Loss

| Quick Response and Long Service Life

| Moisture sensitivity level: Level 1



8.3*8.3*6.0mm



APPLICATION INFORMATION

Communication equipment.

Repeaters, Modems

| Telephone Interface,Line cards.

Data communication equipment.

AGENCY APPROVALS

lcon	Solderability	
RoHS	Compliance with 2011/65/EU	
HF	Compliance with IEC61249-2-21:2003	
®	Mean lead free	
<i>1</i> R °	UL Certificated E505857	

PRODUCT CHARACTERISTICS

Lead Material	Body Material	Terminal Finish	
Copper or Fe-Ni alloy	Ceramics	100% Matte-Tin Plated	



ELECTRICAL PARAMETER

Parameter	Condition	Rating	
DC Spark-over Voltage 1)	100V/s	200-300	
Impulse Spark-over Voltage	At 1kV/μs	for 99 % of measured values ≤700	V
impuise spaik-over voltage	At 1kV/μs	Typical values of distribution ≤650	
Discharge Current (8/20us) 2)	10 times	20	KA
AC Discharge Current	50Hz, 1S	20	
Minimum Insulation Resistance	Test Voltage DC=100V	1	GΩ
Max. Capacitance 1MHz	V _{DC} =0.5V	1.5	
Operating and Storage Temperature		-40~125	°C

¹⁾ In ionized mode

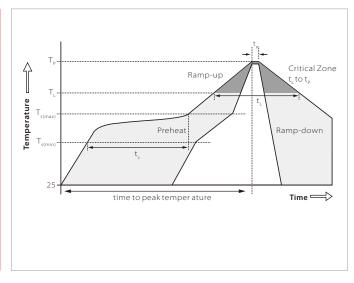
ENVIRONMENTAL RELIABILITY CHARACTERISTICS

Testing items	Technical standards	
High Temperature Storage Test	Temperature: 85°C ; Time:2H	
Low Temperature Storage Test	Temperature: -40°C ; Time:2H	
Vibration	Frequency: 10-500Hz ; Amplitude: 0.15mm ; Time:45min	
Resistance of soldering heat	Temperature: 260±5°C; Time of dip soldering: 10s, 1time	

NOTE: Up-screen program can be specified by customer's request via contacting Semiware service

REFLOW PROFILE

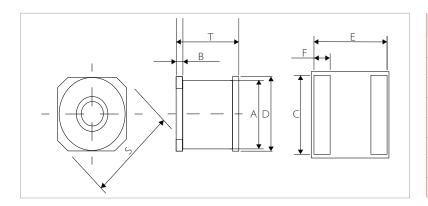
Reflow Condition		Lead-free assembly	
	Temperature Min	150°C	
Pre Heat	Temperature Max	200°C	
	Time(min to max)	60-180 secs	
Average ramp up rate (Liquidus)Temp (T_L) to peak T_s (max)to T_L - Ramp-up Rate		3°C/second max	
Reflow	Temperature (T _L) (Liquidus)	217℃	
Rellow	Temperature (T_L)	60-150 seconds	
PeakTem	kTemperature (T _p) 260+0/-5 °C		
Time within 5°C of actual peak Temperature (tp)		~10 seconds	
Ramp-down Rate		6°C/second max	
Time 25°C to peak Temperature (T,)		8 minutes max.	
Do not exceed		260°C	



²⁾ Terms and waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-21

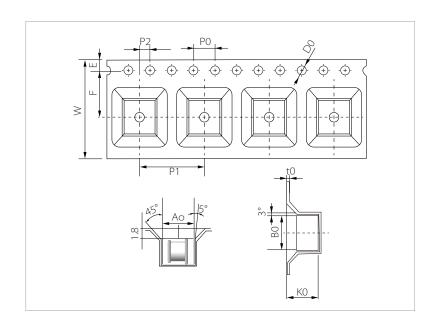


DIMENSIONS AND RECOMMENDED SOLDERING PAD



Ref.	mm
А	8.0±0.2
В	0.5±0.1
С	9.0
D	8.3±0.2
Е	6.7
F	1.2
Т	6.0±0.25
S	9.0±0.4

PACKAGE REEL INFORMATION



Ref.	mm	
W	16.0±0.3	
PO	4.0±0.1	
P1	12.0±0.1	
P2	2.0±0.1	
D0	1.55±0.05	
E	1.75±0.1	
F	7.5±0.1	
AO	6.35±0.1	
KO	6.55±0.1	
ВО	8.65±0.1	
t0	0.5±0.1	

ORDERING INFORMATION

Part Number	Size	Marking	QTY/Reel	Reel Size
SG2R08B250A	8.3*8.3*6.0mm	% SG250 <u>08</u>	600	13″



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